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| Subst. Form PTO-1449 APPLICANT'S(S) INFORMATION DISCLOSURE STATEMENT | | Atty. Dkt No.: LYBZ 2 00084 | | Serial No. 104508734 | |
| | | Applicant(s): DREIFERT | | | |
| | | Filing Date: Herewith | | Group: Confirmation: | |

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| OTHER ART | |
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| Examiner: | Date Considered: |
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